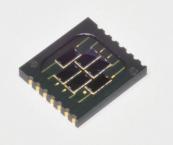


Si PIN photodiode array



S14833

6-element array for encoders

The S14833 is a surface mount type 6-element Si PIN photodiode array. Each of the six elements is separated, and their arrangement is suitable for encoders.

Features

Applications

High sensitivity

Encoders

- Surface mountable chip carrier package
- **■** Compatible with lead-free solder reflow

- Structure

Parameter	Specification	Unit
Number of elements	6	-
Element size	2.76 × 1.37	mm
Package	Glass epoxy	-
Window material	Silicone resin	-

→ Absolute maximum ratings (Ta=25 °C)

Parameter	Symbol	Value	Unit
Reverse voltage	VR max	30	٧
Operating temperature*1	Topr	-40 to +100	°C
Storage temperature*1	Tstg	-40 to +125	°C
Soldering temperature	Tsol	260 (3 times)*2	°C

^{*1:} No dew condensation.

When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

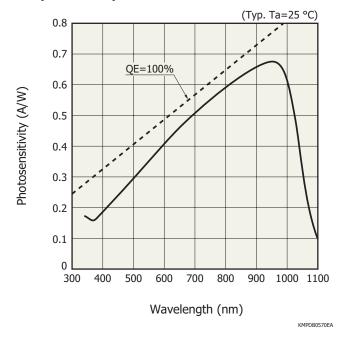
Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

■ Electrical and optical characteristics (Ta=25 °C, per element)

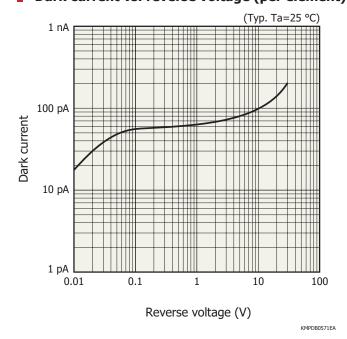
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Spectral response range	λ		-	340 to 1100	-	nm
Peak sensitivity wavelength	λр		-	960	-	nm
Photosensitivity	S	λ=λρ	0.6	0.68	-	A/W
Dark current	ID	VR=10 V	-	-	5.0	nA
Temperature coefficient of ID	ΔTid	VR=10 V	-	1.15	-	times/°C
Cutoff frequency	fc	VR=10 V, RL=50 Ω λ=830 nm, -3 dB	-	10	-	MHz
Terminal capacitance	Ct	VR=10 V, f=10 kHz	-	9	13	pF
Noise equivalent power	NEP	VR=10 V, λ=λp	-	1.6 × 10 ⁻¹⁴	-	W/Hz ^{1/2}

^{*2:} Reflow soldering, JEDEC J-STD-020 MSL 3, See P.5

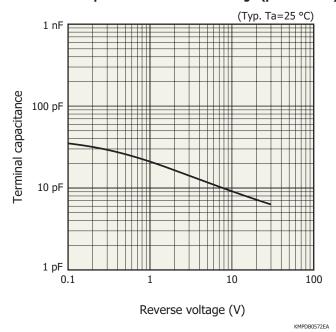
Spectral response



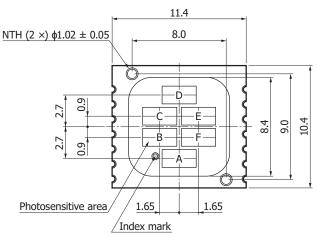
▶ Dark current vs. reverse voltage (per element)

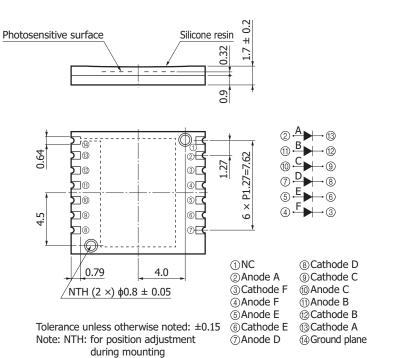


Terminal capacitance vs. reverse voltage (per element)



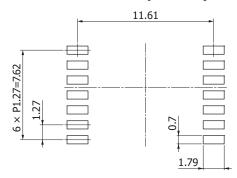
Dimensional outline (unit: mm)





KMPDA0622EA

Recommended land pattern (unit: mm)



- 1. Solder all terminals.
- 2. Do not make the land area larger than necessary.
- 3. It is preferable that the land sizes be about equal.

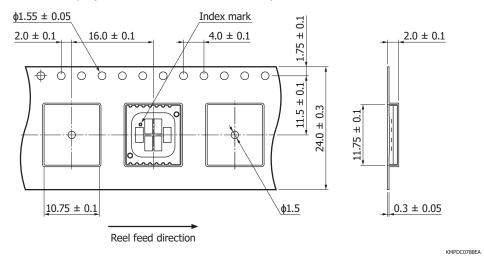
KMPDC0785EA

Standard packing specifications

■ Reel (conforms to JEITA ET-7200)

Outer diameter	Hub diameter	Tape width	Material	Electrostatic characteristics
330 mm	100 mm	24 mm	PS	Conductive

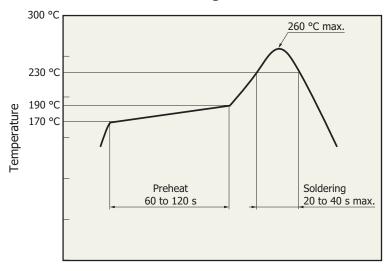
■ Embossed tape (unit: mm, material: PS, conductive)



- Packing quantity 1000 pcs/reel
- Packing state

 Reel and desiccant in moisture-proof packaging (vacuum-sealed)

Recommended reflow soldering conditions



- · After unpacking, keep it in an environment at 5 to 30 °C and a humidity of 60% or less, and perform soldering within 168 hours.
- · The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used.
- · When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

Time

KPINB0385EB

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Surface mount type products
- Technical information
- · Si photodiodes / Application circuit examples

Information described in this material is current as of January 2021.

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